

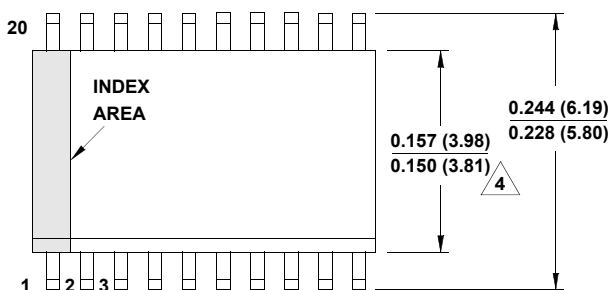
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

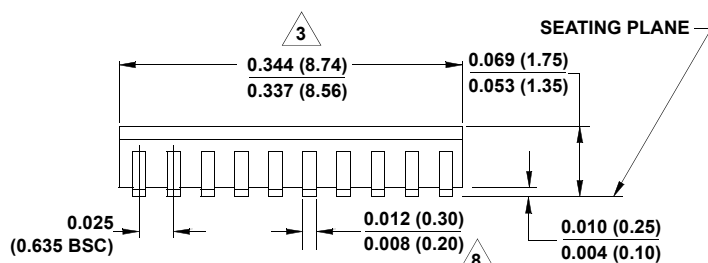
M20.15

20 LEAD QUARTER SIZE OUTLINE PLASTIC PACKAGE (QSOP)

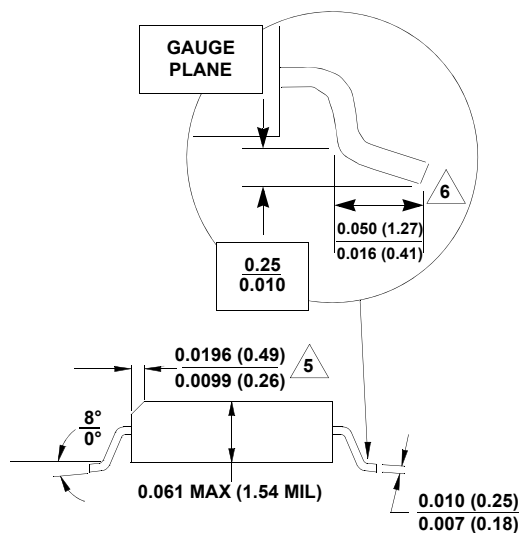
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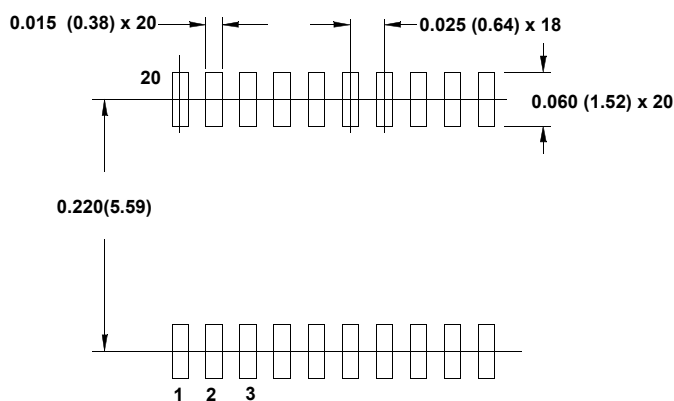
TOP VIEW



SIDE VIEW



DETAIL "X"



TYPICAL RECOMMENDED LAND PATTERN

### NOTES:

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
3. Dimension does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. Length of terminal for soldering to a substrate.
7. Terminal numbers are shown for reference only.
8. Dimension does not include dambar protrusion. Allowable dambar protrusion shall be 0.10mm (0.004 inch) total in excess of dimension at maximum material condition.
9. Controlling dimension: INCHES. Converted millimeter dimensions are not necessarily exact.